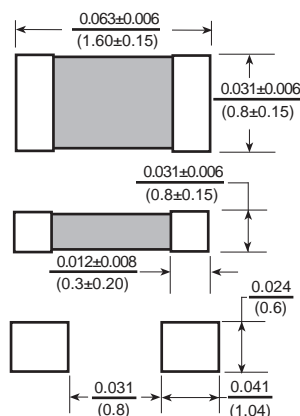
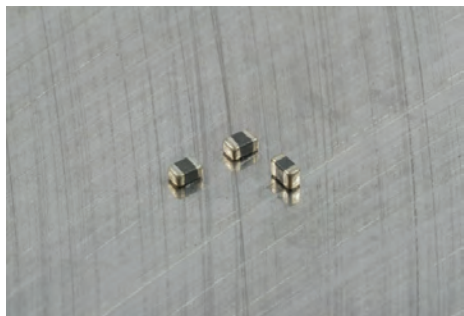




Dimensions: $\frac{\text{Inches}}{\text{(mm)}}$



Allied Part Number	Impedance (Ω) @ 100 MHz +/- 25%	DC Resistance (Ω) Max.	*Rated Current (mA)
MLB05-050-RC	5	0.05	500
MLB05-060-RC	6	0.05	500
MLB05-070-RC	7	0.05	500
MLB05-100-RC	10	0.05	500
MLB05-110-RC	11	0.05	500
MLB05-150-RC	15	0.08	500
MLB05-170-RC	17	0.08	500
MLB05-190-RC	19	0.08	500
MLB05-200-RC	20	0.10	400
MLB05-220-RC	22	0.10	400
MLB05-250-RC	25	0.10	400
MLB05-260-RC	26	0.10	400
MLB05-300-RC	30	0.10	400
MLB05-310-RC	31	0.10	400
MLB05-320-RC	32	0.10	400
MLB05-330-RC	33	0.10	400
MLB05-400-RC	40	0.10	400
MLB05-470-RC	47	0.10	400
MLB05-500-RC	50	0.10	400
MLB05-520-RC	52	0.10	400
MLB05-550-RC	55	0.10	400
MLB05-560-RC	56	0.10	400
MLB05-600-RC	60	0.10	400
MLB05-680-RC	68	0.15	400
MLB05-700-RC	70	0.15	400
MLB05-750-RC	75	0.15	400
MLB05-800-RC	80	0.15	400
MLB05-900-RC	90	0.20	400
MLB05-101-RC	100	0.20	400
MLB05-121-RC	120	0.25	400
MLB05-141-RC	140	0.25	300
MLB05-151-RC	150	0.30	200
MLB05-181-RC	181	0.30	200
MLB05-201-RC	200	0.30	200
MLB05-221-RC	220	0.30	200
MLB05-241-RC	240	0.40	200
MLB05-301-RC	300	0.40	200
MLB05-331-RC	330	0.50	200
MLB05-401-RC	400	0.50	200
MLB05-421-RC	420	0.50	200
MLB05-451-RC	450	0.50	200
MLB05-471-RC	470	0.50	200
MLB05-501-RC	500	0.50	200
MLB05-601-RC	600	0.50	200
MLB05-751-RC	750	0.70	200
MLB05-801-RC	800	0.70	200
MLB05-102-RC	1000	0.70	200
MLB05-122-RC	1200	1.00	50
MLB05-152-RC	1500	1.00	50
MLB05-172-RC	1700	1.20	50
MLB05-202-RC	2000	1.20	50
MLB05-222-RC	2200	1.20	50
MLB05-252-RC	2500	1.30	50
MLB05-272-RC	2700	1.30	50

*Temperature rise $\Delta T = 30^\circ\text{C}$ at rated current.
All specifications subject to change without notice.

Features

- Surface mount EMI suppression components
- Nickel barrier termination for excellent resistance to solder heat
- Multi layer technology
- Flow and reflow soldering

Electrical

Impedance Range: 5Ω to 2700Ω

Tolerance: 25% over entire range

Operating Range: $-55^\circ\text{C} \sim +125^\circ\text{C}$

Storage Temp: Under 25°C at 40–60% Humidity

Rated Current: Based on temp rise not to exceed 30°C

Resistance to Solder Heat

Pre-Heat 150°C , 1 minute

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temp: $260 \pm 5^\circ\text{C}$ for 10sec ± 1 sec.

Minimum of 75% of Electrode covered with new solder.

Impedance within 30% of initial value.

Test Equipment

(Z): HP4291A RF Impedance/Material Analyzer

(RDC): Chen Hwa 502BC

Physical

Packaging: 4000 per 7 inch reel.

Marking: None